IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A system for measuring circuits on an integrated circuit substrate during fabrication, comprising:

a measurement circuit formed on the integrated circuit substrate which measures at least one characteristic of an integrated circuit prior to the integrated circuit being completely fabricated,

the measurement circuit comprising a power transfer device including a power transfer component, which receives energy from a source where the source does not make physical contact with the integrated circuit substrate to transfer power to the measurement circuit when the source is in alignment with the power transfer component, the measurement circuit including components that mirror behavior of the integrated circuit so that process parameters are measured for the components to provide information about processing steps and provide information for determining ~~to determine~~ actions to remedy problems prior to completing fabrication of integrated circuits on the integrated circuit substrate.

2. (Original) The system as recited in claim 1, wherein the integrated circuit substrate includes a chip formed on a semiconductor wafer.

3. (Original) The system as recited in claim 2, wherein the measurement circuit is formed in a kerf area of the chip.

4. (Original) The system as recited in claim 1, wherein the power transfer device includes

an inductor coil and the source transfers energy via inductive coupling.

5. (Original) The system as recited in claim 1, wherein the power transfer device includes a photo sensor and the source transfers energy via light.

6. (Original) The system as recited in claim 5, wherein the photo sensor includes a photodiode and the source includes a laser.

7. (Original) The system as recited in claim 1, wherein the power transfer device includes a capacitor and the source transfers energy via capacitive coupling.

8. (Original) The system as recited in claim 1, wherein the measurement circuit includes a control circuit, which conveys measurement information.

9. (Original) The system as recited in claim 1, wherein the at least one characteristic includes at least one of a layer thickness and a circuit parameter or response.

10. (Currently Amended) A system for measuring circuits on an integrated circuit substrate, comprising:

a semiconductor wafer including a plurality of chips;

a measurement circuit formed on at least one of the chips, the measurement circuit configured to measure at least one characteristic of a partially fabricated integrated circuit,

the measurement circuit including a power transfer component which receives energy

from a source where the source does not make physical contact with the semiconductor wafer to transfer power to the measurement circuit, the measurement circuit including components that mirror behavior of the partially fabricated integrated circuit so that process parameters are measured for the components to provide information about processing steps and provide information for determining ~~to determine~~ actions to remedy problems prior to completing fabrication of integrated circuits on the wafer; and

a test device including the source, which delivers energy to the power transfer component of the measurement circuit when in alignment with the power transfer component.

11. (Original) The system as recited in claim 10, wherein the measurement circuit is formed in a kerf area of the chip.

12. (Original) The system as recited in claim 10, wherein the power transfer component includes an inductor coil and the source transfers energy via inductive coupling.

13. (Original) The system as recited in claim 10, wherein the power transfer component includes a photo sensor and the source transfers energy via light.

14. (Original) The system as recited in claim 13, wherein the photo sensor includes a photodiode and the source includes a laser.

15. (Original) The system as recited in claim 10, wherein the power transfer component includes a capacitor and the source transfers energy via capacitive coupling.

16. (Original) The system as recited in claim 10, wherein the measurement circuit includes a control circuit, which conveys measurement information.

17. (Original) The system as recited in claim 10, wherein the test device includes a thin film dielectric membrane having the source mounted thereon.

18. (Original) The system as recited in claim 10, wherein the test device includes a probe ring.

19. (Original) The system as recited in claim 10, wherein the at least one characteristic includes at least one of a layer thickness and a circuit parameter or response.

20-28. (Cancelled)

29. (Original) The system as recited in claim 17, wherein the thin film dielectric membrane is transparent so that the source mounted thereon can be visually aligned to the power transfer component.